



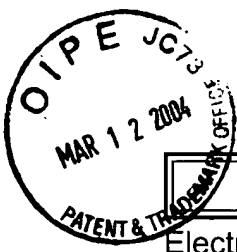
Electronic Filing System (EFS) Data
Electronic Patent Application Submission
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EFS ID: 57019
Application ID: 10706468
Title of Invention: SEMICONDUCTOR PACKAGE
WITH CHAMFERED CORNERS
AND METHOD FOR
MANUFACTURING THE SAME
First Named Inventor: Sung Yang
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-11-12
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Statement
Filing Type:
Confirmation number: 6744
Attorney Docket Number: AMKOR095A



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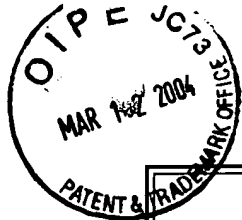


TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	SEMICONDUCTOR PACKAGE WITH CHAMFERED CORNERS AND METHOD FOR MANUFACTURING THE SAME									
Application Number: 10/706468 										
Date: 2003-11-12										
First Named Applicant: Sung Jin Yang										
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Attorney Docket Number: AMKOR095A										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
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Documents being submitted	Files									
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	us-ids.dtd									
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Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of
Invention

SEMICONDUCTOR PACKAGE WITH CHAMFERED
CORNERS AND METHOD FOR MANUFACTURING THE
SAME

Application Number: 10/706468
Confirmation Number: 6744
First Named Applicant: Sung Yang
Attorney Docket Number: AMKOR095A
Art Unit: 2811

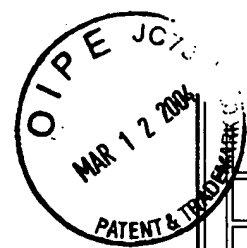


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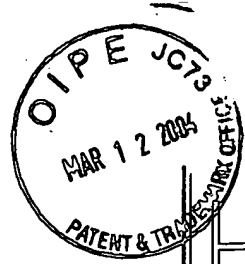
US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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	50	6384472	2002-05-07	HUANG

Signature

Examiner Name	Date